



Material Content Data Sheet



Sales Product Name				IPD5N25S3-430		Issued		25. September 2017	
MA#				MA000921702					
Package				PG-TO252-3-313		Weight*		317.74 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.310	0.41	0.41	4124	4124	
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		464		
	inorganic material	phosphorus	7723-14-0	0.044	0.01		139		
	non noble metal	copper	7440-50-8	147.096	46.28	46.34	462945	463548	
wire	non noble metal	aluminium	7429-90-5	1.054	0.33	0.33	3317	3317	
encapsulation	organic material	carbon black	1333-86-4	1.418	0.45		4462		
	plastics	epoxy resin	-	24.813	7.81		78092		
	inorganic material	silicondioxide	60676-86-0	115.558	36.37	44.63	363687	446241	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11771	11771	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4471	4482	
solder	noble metal	silver	7440-22-4	0.048	0.02		152		
	non noble metal	tin	7440-31-5	0.039	0.01		122		
	non noble metal	lead	7439-92-1	1.846	0.58	0.61	5809	6083	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	copper	7440-50-8	19.177	6.04	6.05	60356	60434	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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